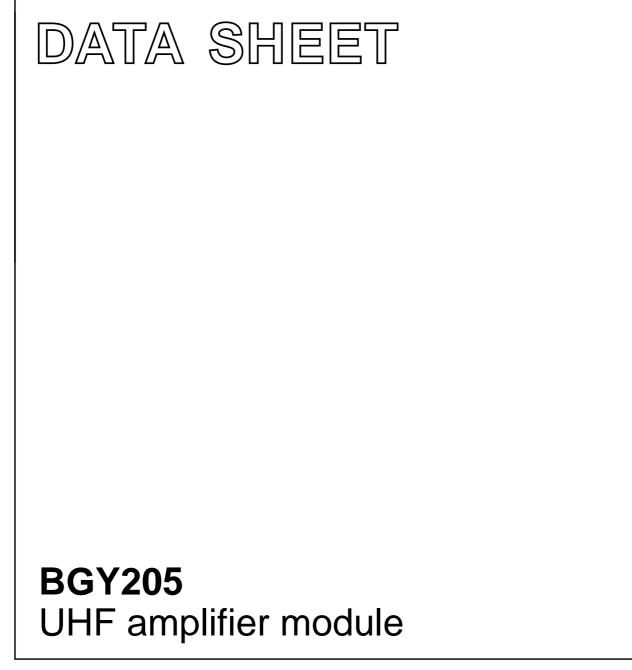
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of May 1994 1996 May 21



### FEATURES

- 6 V nominal supply voltage
- 3.5 W pulsed output power
- Easy control of output power by DC voltage.

### APPLICATIONS

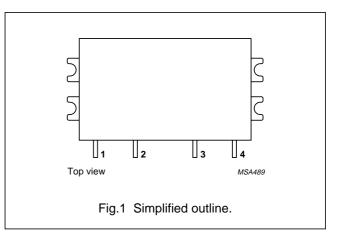
• Digital cellular radio systems with Time Division Multiple Access (TDMA) operation (GSM systems) in the 880 to 915 MHz frequency range.

#### DESCRIPTION

The BGY205 is a four-stage UHF amplifier module in a SOT321B package. The module consists of four NPN silicon planar transistor dies mounted together with matching and bias circuit components on a metallized ceramic substrate.

### PINNING - SOT321B

PIN	DESCRIPTION
1	RF input
2	V <sub>C</sub>
3	Vs
4	RF output
Flange	ground



### QUICK REFERENCE DATA

RF performance at  $T_{mb}$  = 25 °C.

MODE OF	f	V <sub>S</sub>	V <sub>C</sub>	PL	G <sub>p</sub>	η	Z <sub>S</sub> ; Z <sub>L</sub>
OPERATION	(MHz)	(V)	(V)	(W)	(dB)	<b>(%)</b>	(Ω)
Pulsed; δ = 1 : 8	880 to 915	6	≤4	3.5	≥32.5	≥40	50

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### LIMITING VALUES

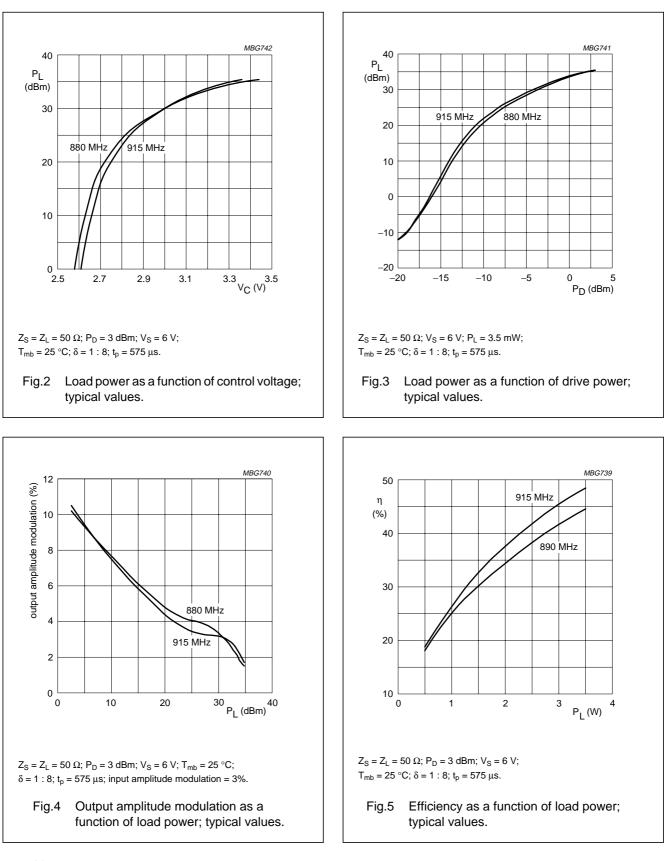
In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER		MAX.	UNIT
Vs	DC supply voltage		8.5	V
V <sub>C</sub>	DC control voltage	-	4.5	V
PD	input drive power	-	7	mW
PL	load power	-	4	W
T <sub>stg</sub>	storage temperature		+100	°C
T <sub>mb</sub>	operating mounting base temperature	-30	+100	°C

#### CHARACTERISTICS

 $Z_S = Z_L = 50 \ \Omega$ ;  $P_D = 3 \ dBm$ ;  $V_S = 6 \ V$ ;  $V_C \le 4 \ V$ ; f = 880 to 915 MHz;  $T_{mb} = 25 \ ^{\circ}C$ ;  $\delta = 1 : 8$ ;  $t_p = 575 \ \mu$ s; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
IQ	leakage current	V <sub>C</sub> = 0.5 V	-	-	100	μA
I <sub>C</sub>	control current	adjust $V_C$ for $P_L = 3.5 W$	-	-	500	μA
PL	load power	$V_{\rm C} = 4 V$	3.5	-	-	W
G <sub>p</sub>	power gain	adjust $V_C$ for $P_L = 3.5 W$	32.5	-	-	dB
η	efficiency	adjust $V_C$ for $P_L = 3.5 W$	40	45	-	%
H <sub>2</sub>	second harmonic	adjust $V_C$ for $P_L = 3.5 W$	-	-	-40	dBc
H <sub>3</sub>	third harmonic	adjust $V_C$ for $P_L = 3.5 W$	-	-	-40	dBc
VSWR <sub>in</sub>	input VSWR	adjust $V_C$ for $P_L = 3.5 W$	-	-	2:1	
	stability	$            P_D = 0 \text{ to } 6 \text{ dBm}; V_S = 5 \text{ to } 8.5 \text{ V}; \\             V_C = 0 \text{ to } 4 \text{ V}; P_L \le 3.5 \text{ W}; \\             VSWR \le 6 : 1 \text{ through all phases} $	_	_	-60	dBc
	isolation	$V_{\rm C} = 0.5 \text{ V}$	-	-	-36	dBm
	control bandwidth	R1 = 0; C1 = 0; see Fig.16	1	-	-	MHz
	AM-AM conversion	$P_D$ with 3% AM; f = 100 kHz; $P_L$ = 3.5 mW to 3.5 W	-	-	12	%
P <sub>n</sub>	noise power	P <sub>L</sub> = 3.5 W; bandwidth = 30 kHz; 20 MHz above transmitter band	-	-	-85	dBm
	ruggedness	$V_S = 8.5 \text{ V}$ ; adjust $V_C$ for $P_L = 3.5 \text{ W}$ ; VSWR $\leq 10 : 1$ through all phases	nc	degradat	tion	



#### MBG735 MBG736 5 5 V<sub>C</sub> (V) P<sub>L</sub> (W) 4 4 3 3 2 2 1 1 0 0 890 910 920 f (MHz) 880 900 880 890 900 910 <sub>f (MHz)</sub> 920 $Z_S = Z_L = 50 \ \Omega$ ; $P_D = 3 \ dBm$ ; $V_S = 6 \ V$ ; $Z_S = Z_L = 50 \ \Omega$ ; $P_D = 3 \ dBm$ ; $V_S = 6 \ V$ ; $V_{C}=4\;V;\,T_{mb}=25\;^{\circ}C;\;\;\delta=1:8;\,t_{p}=575\;\mu s.$ $P_L$ = 3.5 W; $T_{mb}$ = 25 °C; $\delta$ = 1 : 8; $t_p$ = 575 $\mu s.$ Fig.6 Load power as a function of frequency; Control voltage as a function of Fig.7 frequency; typical values. typical values. MBG734 MBG738 -30 10 $H_2, H_3$ phase (deg) (dBc) -40 -10 Н2 -50 H<sub>3</sub> -30 -60 -50 -70 -80 880 -70 890 900 910 <sub>f (MHz)</sub> 920 0 1 2 3 f (MHz)

$$\begin{split} &Z_S = Z_L = 50 \; \Omega; \; \mathsf{P}_D = 3 \; dBm; \; V_S = 6 \; V; \\ &\mathsf{P}_L = 3.5 \; W; \; \mathsf{T}_{mb} = 25 \; ^\circ C; \; \delta = 1:8; \; t_p = 575 \; \mu s. \end{split}$$

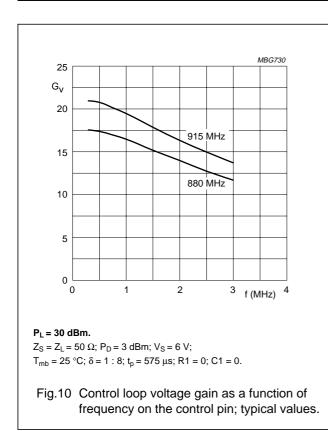
Fig.8 Harmonics as a function of frequency; typical values.

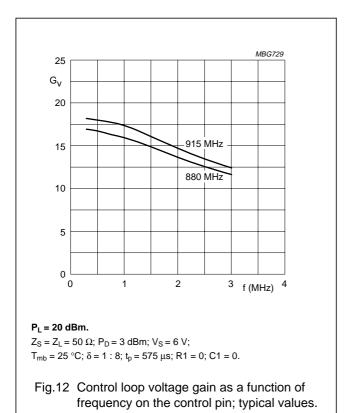
Fig.9 Control loop phase as a function of frequency on the control pin; typical values.

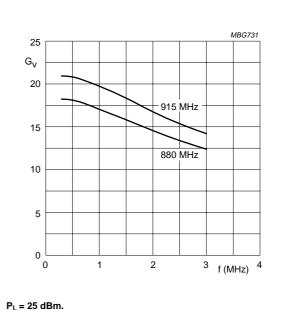
f = 880 to 915 MHz;  $T_{mb}$  = 25 °C;  $\delta$  = 1 : 8;  $t_p$  = 575  $\mu s;$  R1 = 0; C1 = 0.

 $Z_{S} = Z_{L} = 50 \Omega$ ;  $P_{D} = 3 dBm$ ;  $V_{S} = 6 V$ ;  $P_{L} = 15 to 35.4 dBm$ ;

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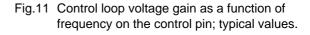






#### $P_L = 25 \text{ dBm.}$ $Z_S = Z_L = 50 \Omega; P_D = 3 \text{ dBm}; V_S = 6 \text{ V};$

 $T_{mb} = 25 \ ^{\circ}C; \ \delta = 1:8; \ t_p = 575 \ \mu s; \ R1 = 0; \ C1 = 0.$ 



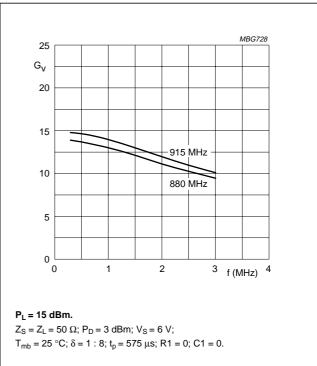
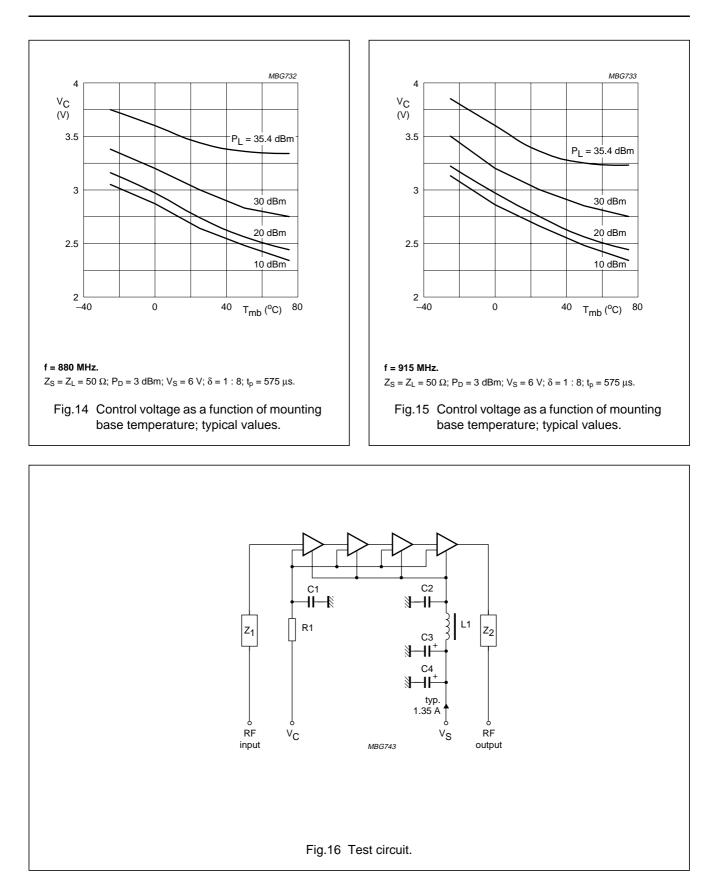
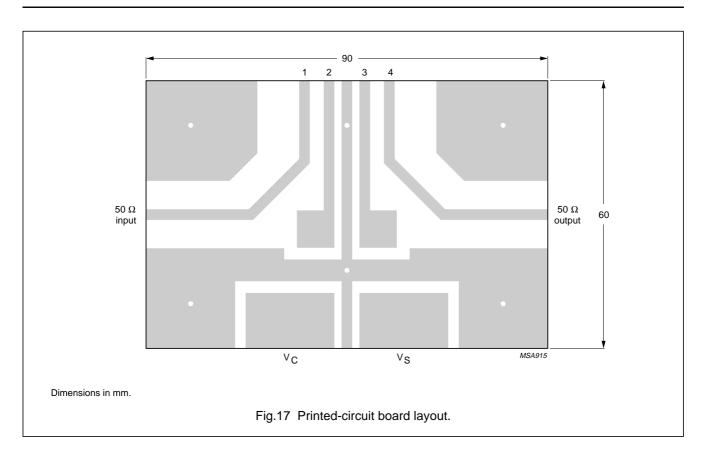


Fig.13 Control loop voltage gain as a function of frequency on the control pin; typical values.



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### List of components (see Fig.16)

COMPONENT	DESCRIPTION	VALUE	DIMENSIONS	CATALOGUE NO.
C1, C2	multilayer ceramic chip capacitor	680 pF		2222 851 11681
C3	tantalum capacitor	2.2 μF; 35 V		-
C4	electrolytic capacitor	47 μF; 40 V		2222 030 37479
L1	Grade 4S2 Ferroxcube bead			4330 030 36300
Z <sub>1</sub> , Z <sub>2</sub>	stripline; note 1	50 Ω	width = 2.33 mm	-
R1	metal film resistor	100 Ω; 0.6 W		2322 156 11001

#### Note

1. The striplines are on a double copper-clad printed-circuit board with PTFE fibreglass dielectric ( $\epsilon_r$  = 2.2); thickness  $\frac{1}{_{32}}$  inch.

### Product specification

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### SOLDERING

The indicated temperatures are those at the solder interfaces.

Advised solder types are types with a liquidus less than or equal to 210  $^\circ\text{C}.$ 

Solder dots or solder prints must be large enough to wet the contact areas.

Footprints for soldering should cover the module contact area +0.1 mm on all sides.

Soldering can be carried out using a conveyor oven, a hot air oven, an infrared oven or a combination of these ovens.

Hand soldering must be avoided because the soldering iron tip can exceed the maximum permitted temperature of 250  $^\circ\text{C}$  and damage the module.

The maximum temperature profile and soldering time is indicated as follows (see Fig.18):

- t = 350 s at 100 °C
- t = 300 s at 125 °C
- t = 200 s at 150 °C
- t = 100 s at 175 °C
- t = 50 s at 200 °C
- t = 5 s at 250 °C (maximum temperature).

#### Cleaning

The following fluids may be used for cleaning:

- Alcohol
- Bio-Act (Terpene Hydrocarbon)
- Triclean B/S
- Acetone.

Ultrasonic cleaning should not be used since this can cause serious damage to the product.

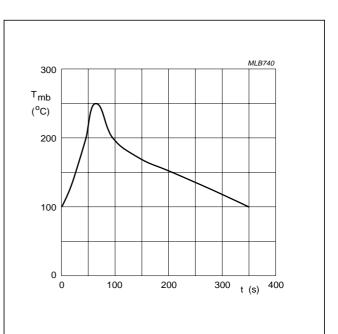
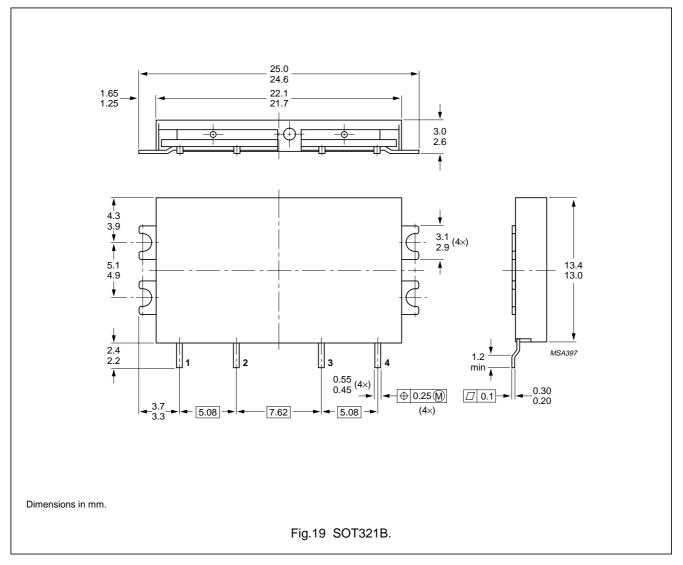


Fig.18 Maximum allowable temperature profile.

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### PACKAGE OUTLINE



**BGY205** 

### DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
more of the limiting values of the device at these or at	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or may cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification limiting values for extended periods may affect device reliability.
Application information	

Where application information is given, it is advisory and does not form part of the specification.

### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.